



Serial No.: 09/523,990

Art Unit 2876

**IN THE CLAIMS**

Please amend the claims to read as follows:

1. (previously presented) A method of marking an electronic integrated circuit chip having surfaces comprising the following steps:

forming internal marking indicia on a marking location upon an exterior surface of the chip for identification of the chip, and

forming an optically transmissive encapsulating material over at least the marking location on the one exterior surface of the chip which optically transmissive material cannot be scraped off of the chip for prevention of replacement of the internal marking indicia by different markings.

2. (previously presented) The method of claim 1 wherein the optically transmissive material comprises a transparent or semi-transparent material.

3. (currently amended) The method of claim 1 wherein the optically transmissive encapsulating material is a protective encapsulating material ~~adapted to provide~~ providing protection from damage as the result of environmental and handling factors.

4. (previously presented) The method of claim 2 including the steps of:  
directing electromagnetic radiation upon the internal marking indicia through the optically transmissive material and  
reading the internal marking indicia in response to images of the internal marking indicia provided by reflections of the electromagnetic radiation.

5. (previously presented) The method of claim 1 wherein the optically transmissive material comprises a colored material.

6. (previously presented) The method of claim 1 wherein the optically transmissive material comprises a material such as epoxy which prevents remarking indicia or identification marks on the chip.

1 7. (previously presented) The method of claim 1 wherein the optically transmissive material  
2 prevents remarking silicon for a semiconductor package and the optically transmissive  
3 material is a transparent material.

1 8. (previously presented) The method of claim 7 including the steps of:  
2 directing electromagnetic radiation upon the internal marking indicia through  
3 the optically transmissive material, and  
4 reading the internal marking indicia in response to images of the internal marking  
5 indicia provided by reflections of the electromagnetic radiation.

1 9. (previously presented) A method of marking an electronic integrated circuit chip having  
2 surfaces comprising the following steps:  
3 forming a semiconductor, integrated circuit chip having surfaces including a planar  
4 front surface, a planar back surface and edges of the chip between the planar surfaces with at  
5 least one electrical contact site on a surface,  
6 forming internal marking indicia upon an exterior marking portion of a surface of the  
7 chip for identification of the chip, and  
8 forming a non-black layer covering the exterior surface of the chip at least at the exterior  
9 marking portion thereof, the non-black layer being composed, of a colored, optically  
10 transmissive material, which non-black layer cannot be scraped off of the chip for preventing  
11 replacement of the internal marking indicia by different markings and for preventing  
12 remarking the internal indicia on the exterior marking surface of the chip,  
13 whereby the indicia are visible through the non-black layer.

1 10. (original) The method of claim 9 including the steps of:  
2 directing electromagnetic radiation upon the internal marking indicia through  
3 the non-black optically transmissive material and  
4 reading the internal marking indicia in response to images of the internal  
5 marking indicia provided by reflections of the electromagnetic radiation.

11. canceled

1 12. (previously presented) A method of marking an electronic integrated circuit chip having  
2 surfaces comprising:

3 forming internal marking indicia on a marking location upon an exterior surface of the  
4 chip, and

5 forming a non-black, optically transparent material colored with a particular color over  
6 at least the marking location on that exterior surface of the chip wherein the material colored  
7 with the particular color together with the marking indicia represents identification of the chip  
8 which non-black, optically transparent, colored material cannot be scraped off of the chip for  
9 prevention of replacement of the internal marking indicia by different markings.

1 13. (previously presented) An electronic integrated circuit chip comprising:

2 the chip having exterior surfaces,

3 internal marking indicia formed on a marking location upon an exterior surface  
4 of the chip for identification of the chip, and

5 an optically transmissive material formed over at least the marking location on the one  
6 exterior surface of the chip which optically transmissive material cannot be easily scraped off  
7 for prevention of replacement of the internal marking indicia by different markings.

1 14. (previously presented) The chip of claim 13 wherein the optically transmissive material  
2 comprises a transparent or semi-transparent material.

1 15. (previously presented) The chip of claim 13 wherein the optically transmissive material  
2 comprises a colored material.

1 16. (previously presented) The chip of claim 13 wherein the optically transmissive material  
2 prevents remarking indicia or identification marks on the chip.

1 17. (previously presented) The chip of claim 13 wherein the optically transmissive material  
2 prevents remarking silicon for a semiconductor package and the optically transmissive material  
3 is a transparent material.

1 18. (previously presented) The chip of claim 13 wherein:  
2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the optically transmissive material and  
4 reading means are provided for reading the internal marking indicia in response to images  
5 of the internal marking indicia provided by reflections of the electromagnetic radiation.

1 19. (currently amended) The chip of claim 13 wherein the optically transmissive material is  
2 ~~adapted to provide~~ providing protection from damage as the result of environmental and  
3 handling factors.

1 20. (previously presented) The chip of claim 14 wherein:  
2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the optically transmissive material and  
4 reading means are provided for reading the internal marking indicia in response to images  
5 of the internal marking indicia provided by reflections of the electromagnetic radiation.

1 21. (previously presented) The chip of claim 17 wherein:  
2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the optically transmissive material and  
4 reading means are provided for reading the internal marking indicia in response to images  
5 of the internal marking indicia provided by reflections of the electromagnetic radiation.

1 22. (previously presented) An electronic integrated circuit chip comprising:

2 a semiconductor, integrated circuit chip having surfaces including a planar front surface,  
3 a planar back surface and edges of the chip between the planar surfaces with at least one  
4 electrical contact site on a surface,

5 indicia marked upon an exterior marking portion of a surface of the chip for identification  
6 of the chip,

7 a cover layer covering the exterior surface of the chip at least at the exterior marking  
8 portion thereof, the cover layer being composed of a colored, optically transmissive material  
9 which optically transmissive material of the cover layer cannot be scraped off of the chip for  
10 prevention of replacement of the indicia by different markings and for preventing remarking  
11 the indicia on the exterior marking surface of the chip, and

12 the indicia being visible through the cover layer.

1 23. (previously presented) The chip of claim 22 wherein:

2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the optically transmissive material and

4 reading means are provided for reading the internal marking indicia in response to images  
5 of the internal marking indicia provided by reflections of the electromagnetic radiation.

24. Canceled

1 25. (currently amended) An electronic integrated circuit chip comprising:

2 internal marking indicia formed on a marking location upon an exterior surface of the  
3 chip, and

4 [[a]] an optically transparent material colored with a particular color formed over at least  
5 the marking location on that exterior surface of the chip wherein the material colored with the  
6 particular color together with the marking indicia represents identification of the chip, which  
7 optically transmissive material cannot be scraped off of the chip for prevention of replacement  
8 of the internal marking indicia by different markings.